

Electronic Patent Application Fee Transmittal

Application Number:	09704529			
Filing Date:	03-Nov-2000			
Title of Invention:	WAFER HAVING CHAMFERED BEND PORTIONS IN THE JOINT REGIONS BETWEEN THE CONTOUR OF THE WAFER AND THE CUT-AWAY PORTION OF THE WAFER			
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Filer:	Ronald J. Shore/Ricardo Perez			
Attorney Docket Number:	501.20289RC6			
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Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Pages:				
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Miscellaneous-Filing:				
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Patent-Appeals-and-Interference:				
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Utility Appl issue fee	1501	1	1440	1440
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
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